

# **SPECIFICATION**

Model No. : SGP.25c

Part No. : **SGP.1575.25.4.C.02** 

Specification No : SP03AB15753-0040(03A28B600011120) (SMA1575A)V03

Product Name : GPS SMT Patch Antenna

Features : 25mm\*25mm\*4.5mm

1575MHz Centre Frequency

Patent pending

**RoHS** ✓

Photo :



#### **REVISION STATUS**

Version	Date	Page	Revision Description	Prepared	Approved
01	17 <sup>th</sup> July 2008	All	New format	TW Product Centre	Ronan Quinlan
02	23 <sup>rd</sup> July 2009	All	New Solder Pads	TW Product Centre	Ronan Quinlan



### 1.0 Introduction

This ceramic GPS patch antenna is based on smart *XtremeGain*<sup>™</sup> technology. It is mounted via SMT process and has been selected as optimal solution for the 45\*45mm ground plane.

# 2.0 Key Antenna Performance Indicators

### Original Patch Specification tested on 45mm ground plane

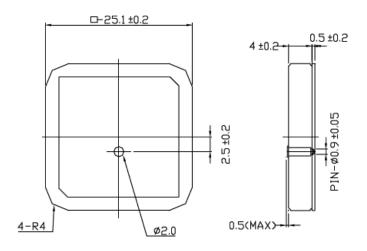
No	Parameter	Specification	Notes	
1	Range of Receiving Frequency	1575.42 MHz ± 1.023 MHz		
	Contor Fraguency	1575.42 ±	With 45mm <sup>2</sup>	
2	Center Frequency	3MHz	ground plane	
			Return Loss ≤-10	
3	Bandwidth	5MHz min	dB	
4	VSWR	1.5 max		
5	Gain at Zenith	+2.0 dBic typ.		
6	Gain at 10°elevation	-3.0 dBic typ.		
7	Axial Ratio	3 dB max		
8	Polarization	RHCP		
9	Impedance	50 Ohms		
	Frequency Temperature	0 ± 20ppm /		
10	Coefficient $(Tf)$	°C	-40ºC to +85ºC	
11	Operating Temperature	-40°C to +85°C		

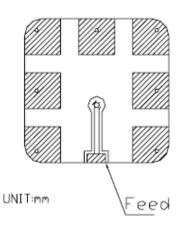
<sup>\*\*</sup>Changes in user groundplane and environment will offset centre frequency



# 3.0 Mechanical Specifications

# 3.1 Dimensions and Drawing

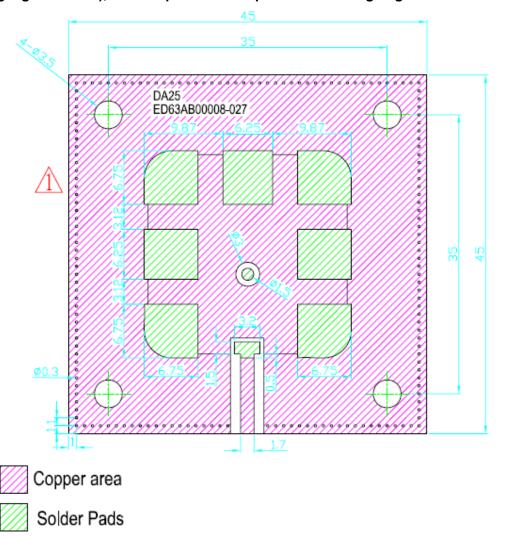






## 3.2 Antenna footprint (view from underneath)

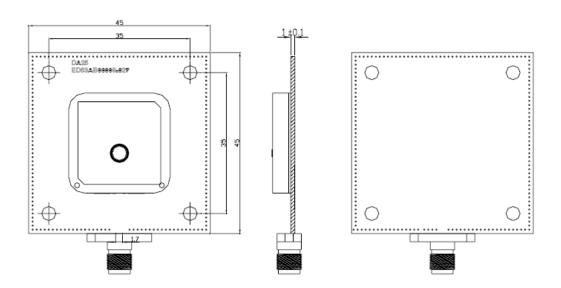
Please note: solder mask has been added to all areas except gold solder areas (green highlighted areas), this will prevent Feed points connecting to ground of main PCB



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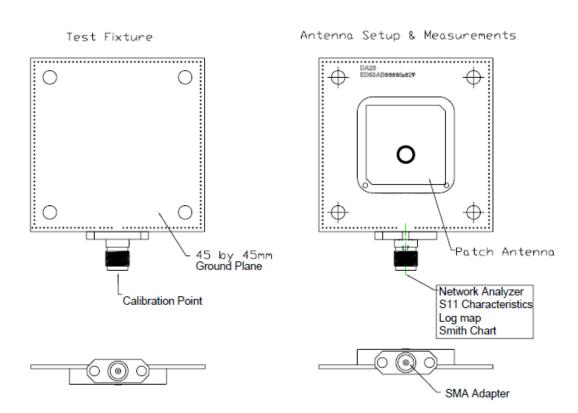
# 3.3 Test Jig and Dimension





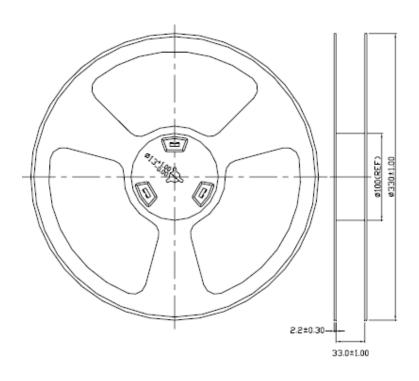


# 3.4 Test Fixture set up and measurements

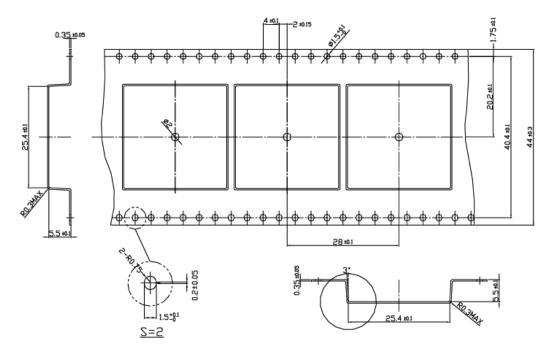




# 3.5 Delivery Mode



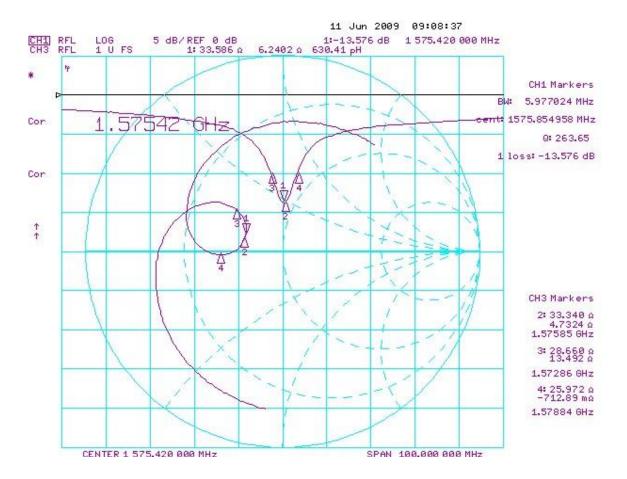






# 4.0 Electrical Specifications

### 4.1 Smith Chart

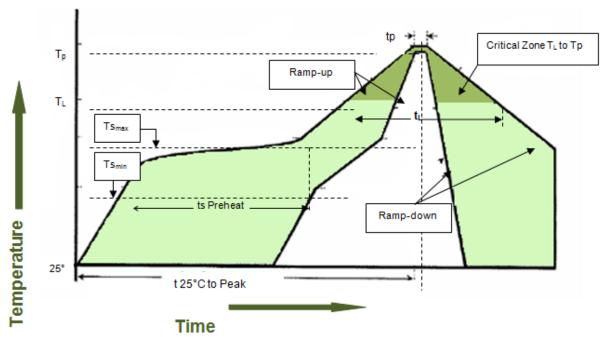




# 5.0 Recommended Reflow Temperature Profile

The SGP.25c can be assembled following either Sn-Pb or Pb-Free assembly processes. The recommended soldering temperatures are as follows:

Phase	Profile Features	Sn-Pb Assembly	Pb-Free Assembly (SnAgCu)
Ramp-Up	Avg Ramp-Up Rate (Tsmax to Tp)	3°C/second (max)	3°C/second (max)
	Temperature Min (Tsmin)	100°	100°
Preheat	Temperature Max (Tsmax)	150°	150°
	Time (tsmin to tsmax)	60-120 seconds	60-120 seconds
Reflow	Temperature (T <sub>L</sub> )	183°C	217°C
Reliow	Total Time Above T <sub>L</sub> b(t <sub>L)</sub>	60-150 seconds	60-150 seconds
Peak	Temperature (Tp)	235°C	260°C
	Time (tp)	10-30 seconds	20-40 seconds
Ramp-Down	Rate	6°C/second (max)	6°C/second (max)
Time from 25°C	to peak Temperature	6 minutes max	8 minutes max



Temperature profile - (green area) for the assembly process in reflow ovens